ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAK® SO-8L					
STRESS	**SAMPLE SIZE**	**DEVICE HR./CYC**	**CONDITION**	**TOTAL FAILS**	**FAIL PERCENTAGE**
BOND INT	720	365 000	200 °C + N2	0	0.00
HAST	2214	221 400	130 °C, 85 % RH	0	0.00
Power Cycle	1066	15 990 000	DELTA T_J = 100 °C	0	0.00
Pressure Pot	2296	220 416	121°, 15 PSIG	0	0.00
Solder DUNK	1045	3135	260 °C, 10 s	0	0.00
Solderability	315	2520	883 M2003	0	0.00
Temp. Cycle	2214	2 214 000	-55 °C to 150 °C	0	0.00

For technical questions, contact: automostechsupport@vishay.com

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